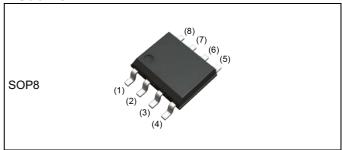
Pch -30V -18A Power MOSFET

V_{DSS}	-30V
R _{DS(on)} (Max.)	5.4mΩ
I _D	±18A
P _D	2.0W

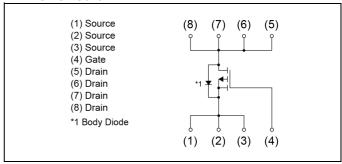
Outline



Features

- 1) Low on resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free lead plating; RoHS compliant

•Inner circuit



Packaging specifications

- 1 donaging opcomeducine						
	Packing	Embossed Tape				
	Reel size (mm)	330				
Туре	Tape width (mm)	12				
	Basic ordering unit (pcs)	2500				
	Taping code	TB1				
	Marking	RS3E180AT				

Application

Switching

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	-30	V
Continuous drain current	I _D	±18	Α
Pulsed drain current	I _{DP} *1	±72	Α
Gate - Source voltage	V _{GSS}	±20	V
Avalanche current, single pulse	I _{AS} *2	-18	Α
Avalanche energy, single pulse	E _{AS} *2	81	mJ
Decree discipation	P _D *3	2.0	W
Power dissipation	P _D *4	1.4	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Doromotor	Symbol	Values			I India
Parameter		Min.	Тур.	Max.	Unit
Thermal registance innetion, ambient	R _{thJA} *3	-	-	62.5	°C/W
Thermal resistance, junction - ambient	R _{thJA} *4	-	-	89.2	°C/W

● Electrical characteristics (T_a = 25°C)

Davamatav	Cymah al	Conditions	Values			Lloit
Parameter Symbol Col		Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = -1mA$	-30	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = -1mA referenced to 25°C	-	-22	-	mV/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V	1	-	-1	μA
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	-	±500	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -5mA$	-1.0	-	-2.5	V
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I _D = -1mA referenced to 25°C	-	2.9	-	mV/°C
Static drain - source	D *5	V _{GS} = -10V, I _D = -18A	ı	4.1	5.4	mO
on - state resistance	R _{DS(on)} *5	$V_{GS} = -4.5V, I_D = -18A$	-	5.0	6.1	mΩ
Gate resistance	R_G	f = 1MHz, open drain	-	3.0	-	Ω
Forward Transfer Admittance	Y _{fs} * ⁵	V _{DS} = -5V, I _D = -18A	22	-	-	S

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} L \simeq 0.5mH, V_{DD} = -15V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*3} Mounted on a ceramic board (30×30×0.8mm)

^{*4} Mounted on a Cu board (25×25×0.8mm)

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C)

Darameter	Cumbal	Conditions		Unit			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	UIIIL	
Input capacitance	C _{iss}	V _{GS} = 0V	-	7200	1		
Output capacitance	C _{oss}	V _{DS} = -15V	-	1300	1	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	1010	1		
Turn - on delay time	t _{d(on)} *5	V _{DD} ≃ -15V,V _{GS} = -10V	1	26	1		
Rise time	t _r *5	I _D = -9A	-	49	1	no	
Turn - off delay time	t _{d(off)} *5	R _L ~ 1.6Ω	-	295	1	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	245	-		

●Gate charge characteristics (T_a = 25°C)

Doromotor	Symbol	Conditions -		Values			Lleit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate charge	O *5		V _{GS} = -10V	ı	160	1	
Total gate charge	Q _g *5	V _{DD} ≃ -15V		-	80	-	~ C
Gate - Source charge	Q _{gs} *5	I _D = -18A	V _{GS} = -4.5V	-	25	-	nC
Gate - Drain charge	Q _{gd} *5			-	31	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Darameter	Cumb of	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I _S	T = 25°C	-	-	-1.67	Α
Pulse forward current	I _{SP} *1	T _a = 25℃	-	-	-72	Α
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = -1.67A	-	-	-1.2	V

Fig.1 Power Dissipation Derating Curve

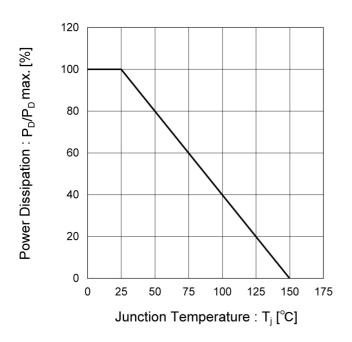
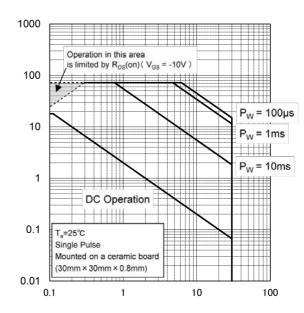


Fig.2 Maximum Safe Operating Area



Drain Current : -I_D [A]

Drain - Source Voltage : -V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

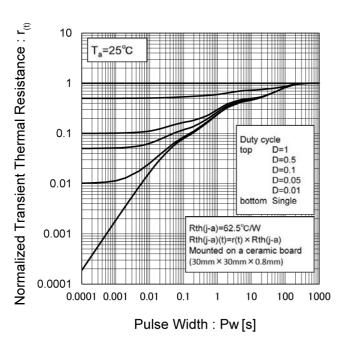
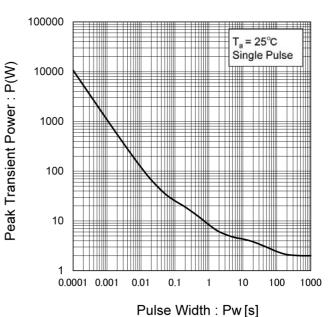


Fig.4 Single Pulse Maximum Power dissipation



i disc width. i w [s]

Drain Current : -I_D [A]

Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

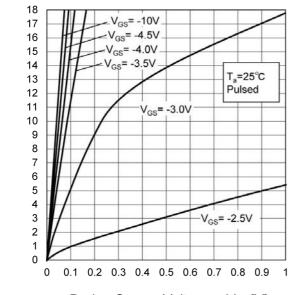
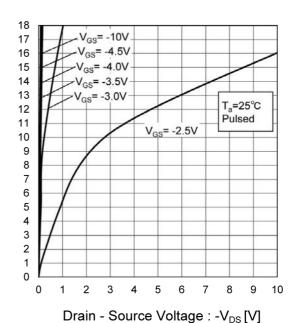


Fig.6 Typical Output Characteristics(II)



Drain Current : -I_D [A]

Drain - Source Voltage : - $V_{DS}[V]$

Fig.7 Breakdown Voltage vs.

Junction Temperature

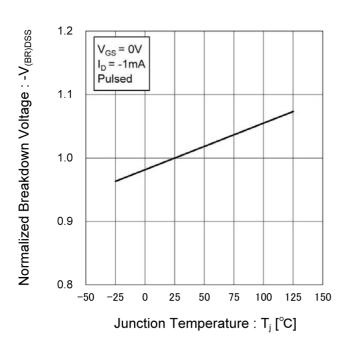


Fig.8 Typical Transfer Characteristics

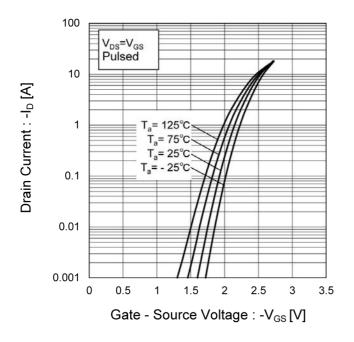


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

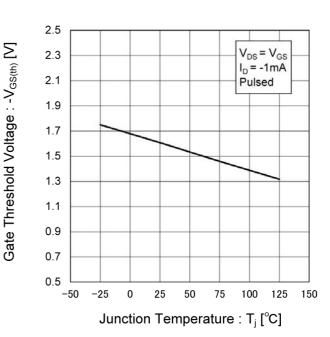
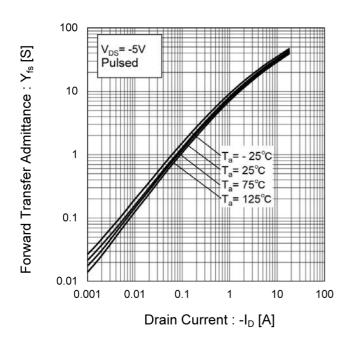


Fig.10 Forward Transfer Admittance vs.
Drain Current



6/11

Fig.11 Drain Current Derating Curve

120 100 Drain Current Dissipation 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

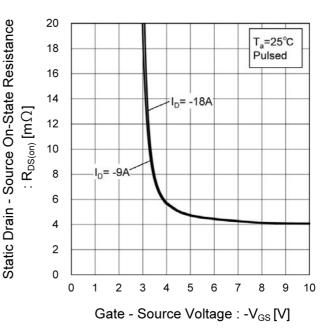


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

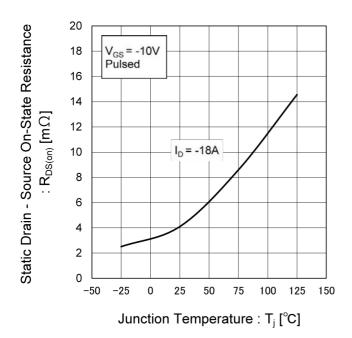


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

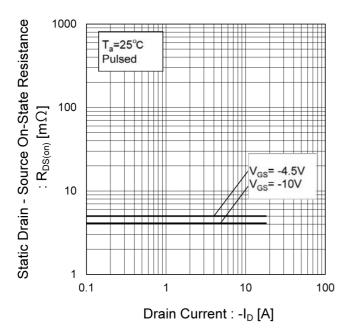


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

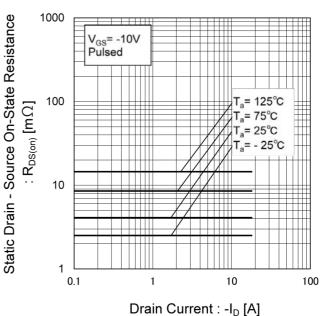
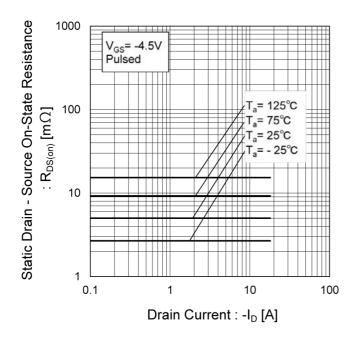


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



8/11

Fig.17 Typical Capacitance vs.

Drain - Source Voltage

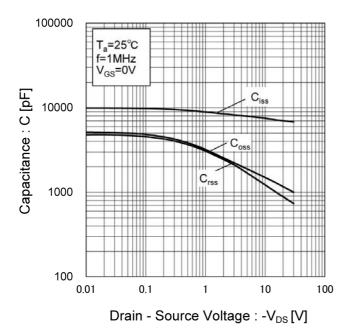


Fig.18 Switching Characteristics

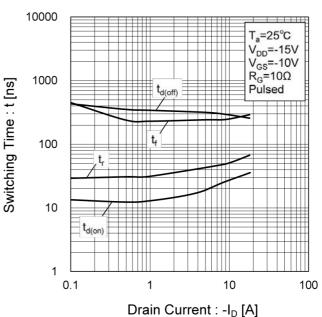


Fig.19 Dynamic Input Characteristics

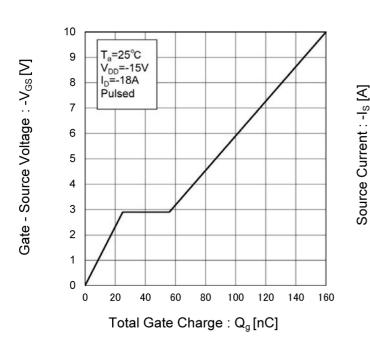
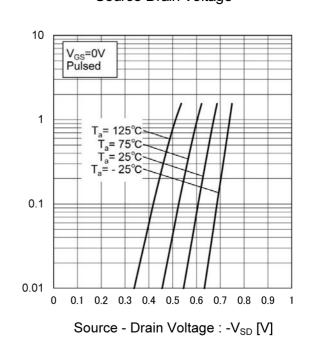


Fig.20 Source Current vs.

Source Drain Voltage



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

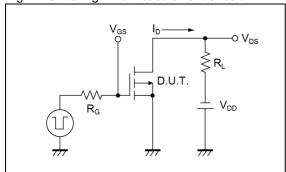


Fig.2-1 Gate Charge Measurement Circuit

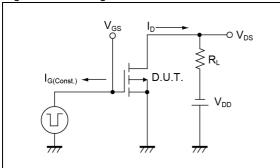


Fig.3-1 Avalanche Measurement Circuit

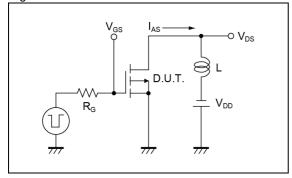


Fig.1-2 Switching Waveforms

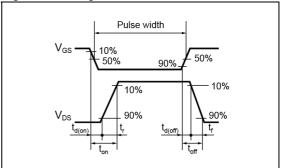


Fig.2-2 Gate Charge Waveform

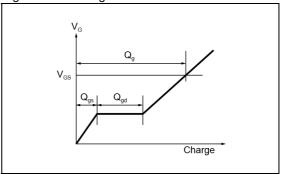
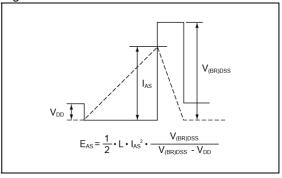
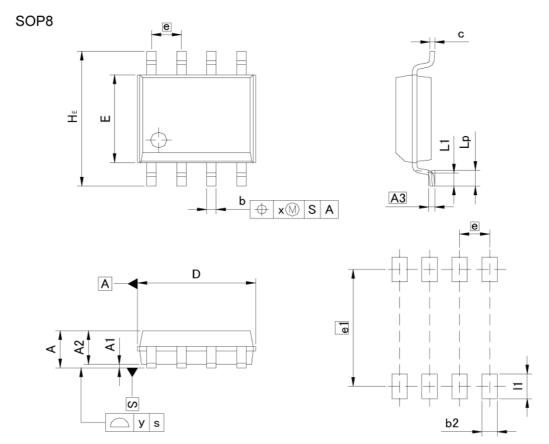


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	<u>₽3</u>	1.75	= 1	0.069	
A1	0.	15	0.0	06	
A2	1.40	1.60	0.055	0.063	
A3	0.:	25	0.0	10	
b	0.30	0.50	0.012	0.020	
С	0.10	0.30	0.004	0.012	
D	4.80	5.20	0.189	0.205	
E	3.75	4.05	0.148	0.159	
е	1.3	27	0.050		
HE	5.70	6.30	0.224	0.248	
L1	0.40	0.60	0.016	0.024	
Lp	0.65	0.85	0.026	0.033	
x	0.	15	0.0	06	
у	0.10		0.004		
	MILIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
b2		0.65		0.026	

Dimension in mm/inches

e1 11



0.045

0.203

1.15

5.15

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Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	CLASSⅢ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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